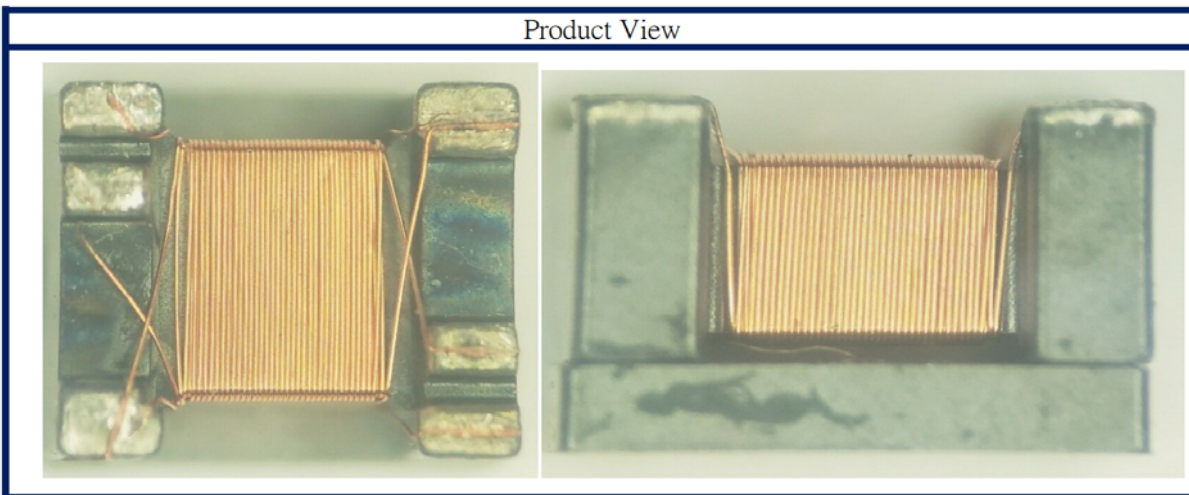


Lan Transformer

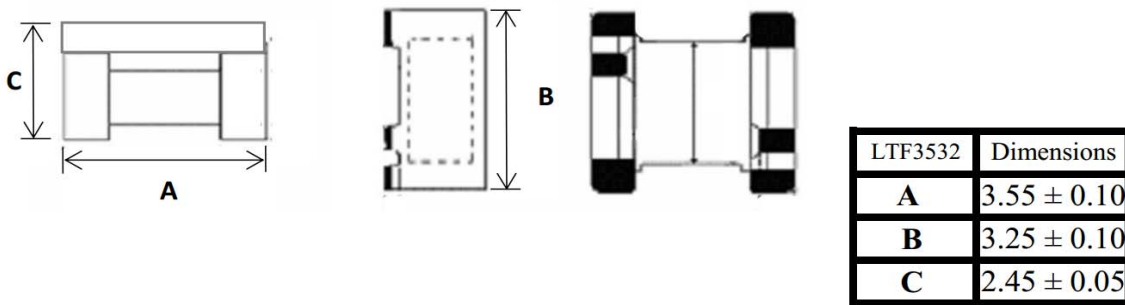
LTF3532-6P-121-T type

Product View

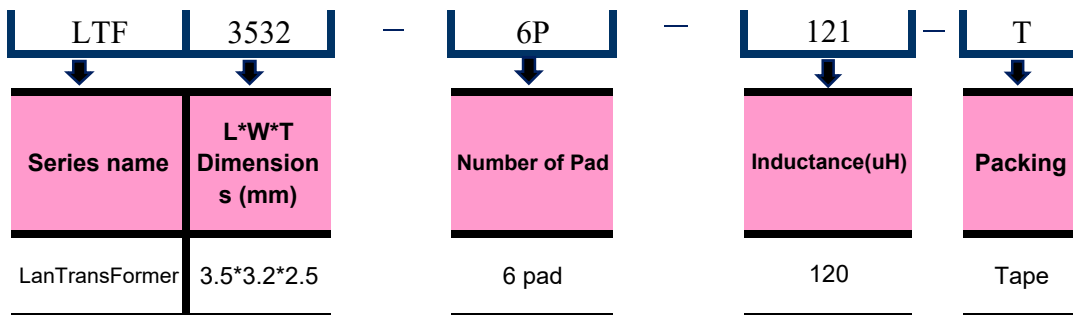




◆ SHAPE & DIMENSIONS



◆ PART NUMBER CONSTRUCTION



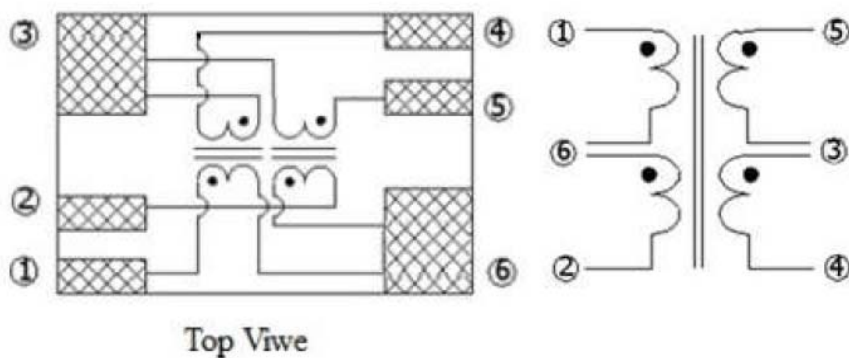
◆ OPERATING TEMPERATURE RANGE, PACKAGE QUANTITY.

Type	Temperature range		Reel Dimensions	Package quantity
	Operating Temperature °C	Storage Temperature °C	(mm)	(pieces/reel)
LTF3532 TYP	-40 to +85	-40 to +85	ø180	1,000

◆ ELECTRICAL CHARACTERISTIC

Turns ratio 1-2 , 4-5	Inductance [100KHz,0.1V] 1-2 , 4-5	Insertion Loss (Max)	Cp Capacitance 3-6 (pF)	Hi-Pot / 5mA 1-3 , 4-6	Part No.
1:1	120uH (Min)	1M-100MHz -1.0dB (Max)	35pF MAX	Pass 1.5KV/60sec	LTF3532-6P-121-T

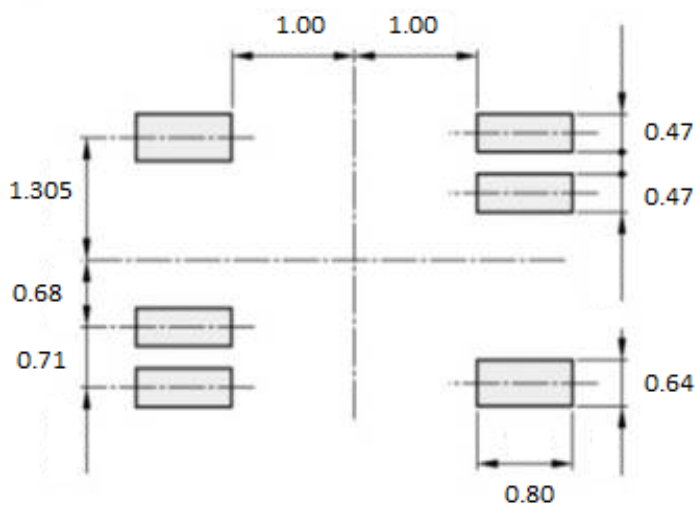
◆ Schematic Diagram



◆ Measurement

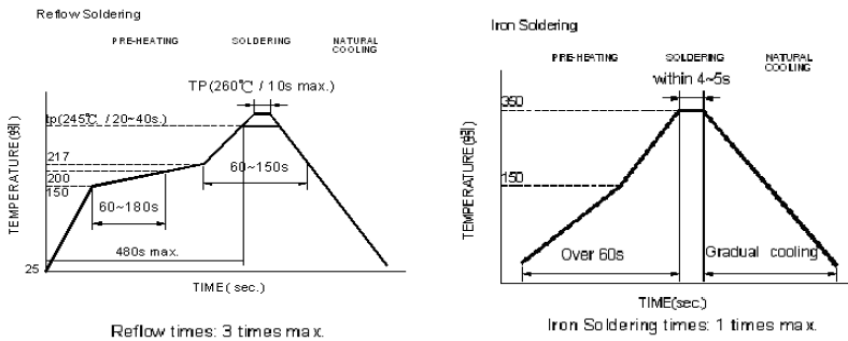
Measurement Item	Meter	Manufacturer
Inductance	TH2830	Tonghul
Insertion loss	E5071C	Keysight
Capacitance	TH2830	Tonghul

◆ Recommended Soldering Conditions (Please use this product by reflow soldering)



◆ RECOMMENDED REFLOW PROFILE

2019/5/31



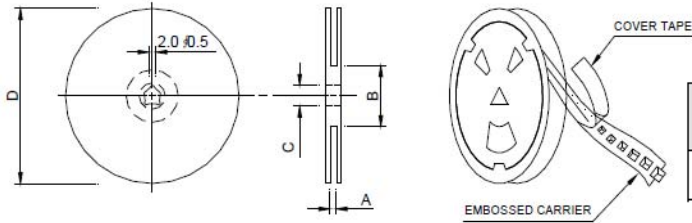
◆ MECHANICAL RELIABILITY

TEST ITEM	Specification & Requirement	Method Used												
Solderability	The surface of terminal/pin tested shall be covered with new solder by 90%	Solder heat proof: Preheating: 150 ±10°C 60 seconds Soldering: 245 ±5°C for 4 ±1 sec												
Solder Heat Resistance	Components should have not evidence of Impedance: within ±15% of initial value	Preheating: 150°C 60secs Flux: rosin Dip time: 10±0.5 secs												
Terminal strength	<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 40%;">Series No.</th> <th style="width: 20%;">F (Kg)</th> </tr> </thead> <tbody> <tr><td style="text-align: center;">2012</td><td style="text-align: center;">0.5</td></tr> <tr><td style="text-align: center;">2520</td><td style="text-align: center;">1.0</td></tr> <tr><td style="text-align: center;">3216</td><td style="text-align: center;">1.0</td></tr> <tr><td style="text-align: center;">3225</td><td style="text-align: center;">1.0</td></tr> <tr><td style="text-align: center;">3532</td><td style="text-align: center;">1.0</td></tr> </tbody> </table>	Series No.	F (Kg)	2012	0.5	2520	1.0	3216	1.0	3225	1.0	3532	1.0	Solder a chip to test substrate and then laterally apply a force in the arrow direction
Series No.	F (Kg)													
2012	0.5													
2520	1.0													
3216	1.0													
3225	1.0													
3532	1.0													

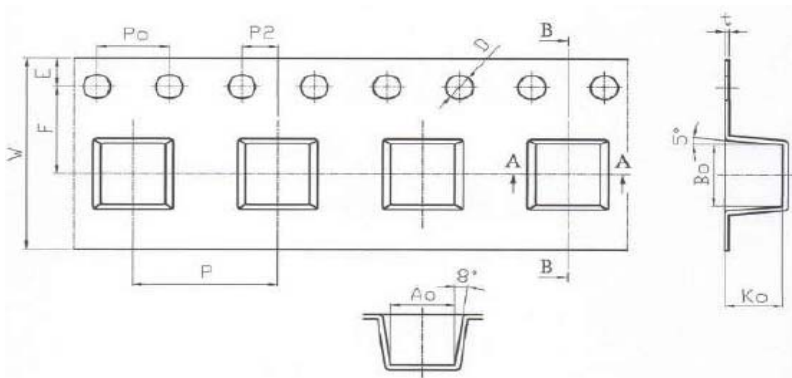
ENDURANCE RELIABILITY

Thermal Shock	Impedance change within ± 15% Without mechanical damage	-65°C, (30 mins) -> room temp. (2 mins) 125°C, (30 mins) -> room temp. (2 mins) 50 cycles
Humidity Resistance		Apply IDC current @ 60°C ambient Humidity: 90% Duration: 168 hrs
Low Temp. Storing		Storing Temp. -40 ±2 °C for total 168 +5/-0 hours
High Temp. Storing		Storing Temp. 125 ±2 °C for total 168 +5/-0 hours

◆ Reel Dimension & Tape Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x12mm	12.5±0.5	100±2	13.5±0.5	330

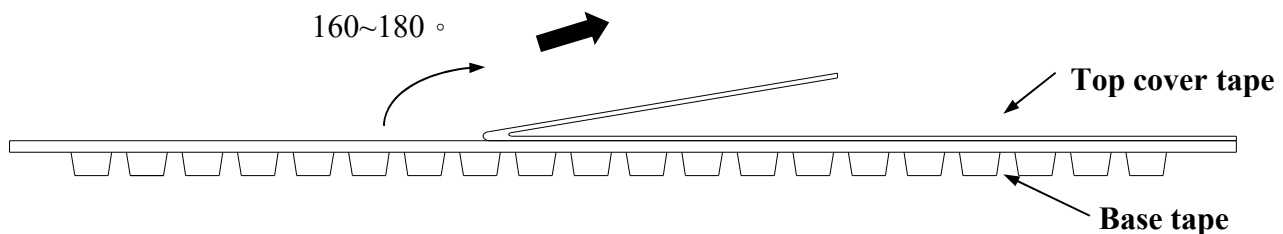


Series	P(mm)	P0(mm)	P2(mm)	B0(mm)	A0(mm)	K0(mm)	D(mm)	E(mm)	F(mm)	W(mm)	t(mm)
TNH353229NF	8.00±0.10	4.00±0.10	2.00±0.05	3.90±0.10	3.55±0.10	3.20±0.10	1.05+0.10/-0.00	1.75±0.10	5.50±0.05	12.00±0.10	0.30±0.05

◆ Cover Tape Peel Strength

The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed (mm/min)
5~35	45~85	860~1060	300



◆ Packaging Quantity

Chip Size	Chip/Reel	Inner Box	Carton
12mm / Reel	2000	4000	32000